



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ12DN20NS3 G	Issued	17. February 2022
MA#	MA005698465		
Package	PG-TSDSON-8-2	Weight*	38.45 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.374	3.57	3.57	35738	35738
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55	
	non noble metal	zinc	7440-66-6	0.008	0.02		218	
	non noble metal	iron	7439-89-6	0.168	0.44		4361	
	non noble metal	copper	7440-50-8	6.808	17.71	18.18	177074	181708
wire	non noble metal	copper	7440-50-8	0.049	0.13	0.13	1268	1268
encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		899	
	plastics	epoxy resin	-	1.780	4.63		46303	
	inorganic material	silicondioxide	60676-86-0	15.468	40.23	44.95	402343	449545
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10070	10070
plating	noble metal	silver	7440-22-4	0.963	2.50	2.50	25038	25038
solder	non noble metal	tin	7440-31-5	0.030	0.08		793	
	noble metal	silver	7440-22-4	0.038	0.10		991	
	non noble metal	lead	7439-92-1	1.455	3.79	3.97	37854	39638
heat sink clip	inorganic material	phosphorus	7723-14-0	0.002			49	
	non noble metal	zinc	7440-66-6	0.008	0.02		196	
	non noble metal	iron	7439-89-6	0.151	0.39		3925	
	non noble metal	copper	7440-50-8	6.127	15.94	16.35	159374	163544
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			28	
	non noble metal	zinc	7440-66-6	0.004	0.01		112	
	non noble metal	iron	7439-89-6	0.086	0.22		2243	
	non noble metal	copper	7440-50-8	3.501	9.11	9.34	91068	93451
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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